

B.Tech. IIIrd Semester (Main/Back) Examination, Feb. - 2011
Electronics & Communication Engineering
3EC5 Electronic Materials and Processes

Time : 3 Hours

Maximum Marks : 80

Min. Passing Marks : 24

Instructions to Candidates:

Attempt overall five questions, selecting one question from each unit. Schematic diagrams must be shown wherever necessary. Any data you feel missing may suitably be assumed and stated clearly.

Unit - I

1. a) Prove the Clausius - Mosotti relation (8)

$$\frac{\epsilon_r^* - 1}{\epsilon_r^* + 2} = \frac{1}{3\epsilon_0} N(\alpha_e + \alpha_i)$$

approximate this relation at IR (infra red) region.

- b) Explain the interfacial polarization and its dynamic response. Draw its frequency spectra and dipolar relaxation. (8)

OR

- a) Derive the temperature - independent condition. (4)

$$\frac{1}{L} \frac{dL}{dT} + \frac{1}{C} \frac{dC}{dT} = 0$$

For a resonant tank circuit.

- b) For a solid contains 5×10^{28} atoms/m³ with polarizability 2×10^{-38} farad m². Find the strength ratio of internal field to external applied field for Lorentz distribution. (6)

- c) Draw the polarization with applied field for (3+3=6)

- i) Ferro Electric and
 ii) Antiferro Electric Materials.

Unit - II

2. a) Draw the susceptibility with temperature for Dia, Para, ferro, ferri and antiferromagnetic materials. (5×2=10)
- b) The Magnetic field strength in a piece of copper is 10^6 ampere m^{-1} . Given that the Magnetic susceptibility of copper is -0.5×10^{-5} , find the flux density and the Magnetization in the copper. (6)

OR

- a) Define (3×4=12)
- i) initial permeability
 - ii) remenant magnetization
 - iii) coercive force
 - iv) saturation magnetization
- On BH loop for a soft magnetic material. Compare their values from a Hard magnetic material.
- b) Explain the Domain theory, Domain growth under magnetization and domain walls for a ferromagnetic materials. (4)

Unit - III

3. a) Write three difference for each (3×4=12)
- i) Degenerate and Non-degenerate semiconductor material.
 - ii) GaAs and Si semiconductor.
 - iii) EGS (Electronic Grade Silicon) and MGS (Mechanical Grade Silicon).
 - iv) Direct and Indirect Band gap semiconductors.
- b) Derive the continuity equation for P-type semiconductor that is illuminated and open-circuit. (4)

OR

- a) A compound semiconductor is given by $\begin{pmatrix} Al & Ga & As \\ 1-x & x & y \end{pmatrix} \cdot \frac{P}{1-y}$ then find the value of x & y for give the effective Bandgap $E_g = 3.8$ ev. Given that Bandgap of $AlAs \rightarrow 3.8$ ev $GaAs \rightarrow 1.4$ ev
 $P \rightarrow 4.2$ ev.

Also find the corresponding wavelength for which it responds maximum.

(2+6=8)

- b) How control or, depends the purity / defects on (4×2=8)
- i) temperature gradient
 - ii) pulling / zone refining speed
 - iii) zone cross section / diameter of the ingot
 - iv) no. of cycles of zone refine
- in a zone refining process.

Unit - IV

4. a) Define (5×2=10)
- i) Mean free path
 - ii) Relaxation time
 - iii) Fermi velocity
 - iv) Scattering points
 - v) Drift velocity for electrons
- b) Derive the relation and (6)

$$\sigma(\omega) = \frac{\sigma_0}{1 + \omega^2 \tau^2}$$

for metals, draw $\sigma(\omega)$ with frequency.

OR

- a) Define the following conduction phenomena (3×3=9)
- i) Hopping conduction
 - ii) Diffusion conduction
 - iii) Drift conduction.
- Also state the conditions for which above phenomena applicable.
- b) Write four differences between Type I and Type II semiconductor. Write the basis of BCC theory of superconductivity. (7)

Unit - V

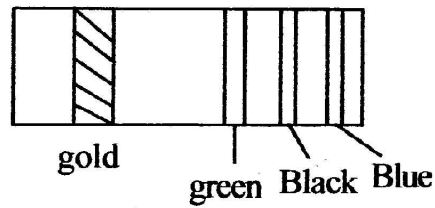
5. a) Write the name of Mostly used capacitors used for the range (4×2=8)
- i) below picofarrad
 - ii) nano - picofarrad
 - iii) microfarrad
 - iv) millifarrad.

Also write their power range and mechanical structures.

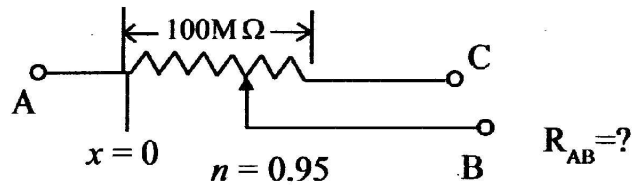
b) Calculate the value of resistors

(2+2+4=8)

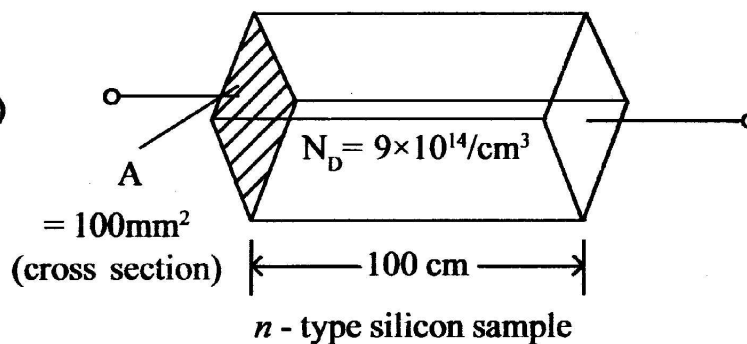
i)



ii)



iii)



having $n_i = 1.5 \times 10^{10}/\text{cm}^3$

$$K_n = 1400 H_p = 300 \frac{M^2 \cdot \text{volt}}{\text{Secs.}}$$

OR

Write short notes on any four :

(4×4=16)

- SOI
- Ferrite/hexaferrite core with silicon doping
- Laminated transformer core
- Double layer PCB
- Variable inductors.